

Attorney's Docket No. <u>016660-055</u>

In re Patent Application of)
Wing Cheung HO et al) Group Art Unit: 1725
Application No.: 09/649,084) Examiner: L. Edmondson
Filed: August 28, 2000) Confirmation No.: 7505
For: WIRE-BONDING APPARATUS)
WITH IMPROVED XY-TABLE)
ORIENTATION)

AMENDMENT

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

In response to the Office Action dated March 19, 2002, kindly amend the aboveidentified application as follows:

IN THE CLAIMS:

- 1. (Thrice Amended) Wedge wire bonding apparatus comprising:
 - (a) means for supporting a workpiece,
 - (b) a bonding head including a transducer having a longitudinal axis,
 - (c) means for causing relative move.

 transducer along an X axis,

 (d) means for causing relative movement of the workpiece and the RECEIVED

 To a long a Y axis orthogonal to said X axis, and

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